# Bill of Materials

| Item | Qty | Reference | Value | Part Description | Manufacturer | Manufacturer Part Number | Digikey PN | Notes |
|---|---|---|---|---|---|---|---|---|
| 1 | 1 | JTAG | N/A | CONN HEADER 14 POS STRGHT GOLD | 3M | N2514-6002-RB | MHC14K-ND | |
| 2 | 4 | UP, DOWN, MODE1, MODE2 | N/A | SWITCH TACTILE SPST-NO 0.02A 15V | Panasonic | EVQ-21304M | P12216SCT-ND | |
| 3 | 4 | J1, J2, KNX_R, KNX_L | N/A | Conn Socket Strip SKT 10 POS 2.54mm | Samtec | SSQ-110-01-L-S | N/A | |
| 4 | 2 | LCD_R, LCD_L, JP7 | N/A | CONN HEADER .100" SNGL STR 10POS | Sullins Connector | PRPC010SAAN-RC | S1011EC-10-ND | |
| 5 | 1 | JP5 | N/A | Conn Socket Strip SKT 14 POS 2.54mm | Samtec | SSQ-107-01-F-D | N/A | |
| 6 | 3 | R1, R2, R3 | 5.1kΩ | RES SMD 5.1K OHM 5% 1/16W 0402 | Stackpole Electronics Inc. | RMCF0402JT5K10 | RMCF0402JT5K10DKR-ND | |
| 7 | 1 | C1 | 0.1uF | CAP CER 0.1UF 16V X7R 0402 | Yageo | CC0402KRX7R7BB104 | 311-1338-1-ND | |
| 8 | 1 | J7 | N/A | BOARD EVAL FOR HDC1000 | Texas Instruments | HDC1000EVM | 296-38034-ND | Either HDC1000 or HDC1000EVM required. Not both |
| 9 | 1 | U1 | N/A | Low Power, 3% Accuracy Digital Humidity Sensor with Integrated Temperature Sensor | Texas Instruments | HDC1000 | N/A | Either HDC1000 or HDC1000EVM required. Not both |
| 10 | 2 | TP+,TP- | N/A | Tubular plug pin for wire 1364 E Ms sn 10x3.5 | Vogt AG Verbindungstechnik | 1364e.68 | N/A | |
| 11 | 1 | N/A | N/A | Connector; for EIB applications | Wago | 243-212 | N/A | Female connector for twisted pair bus |
| 12 | 1 | KNX PHY | N/A | Siemens TPUART media module | Tapko Technologies | P.114.20.4111 | N/A | Only one media module required. Solution supports all |
| 13 | 1 | KNX PHY | N/A | Siemens TPUART2 medial module | Tapko Technologies | P.114.20.4211 | N/A | Only one media module required. Solution supports all |
| 14 | 1 | KNX PHY | N/A | On Semi NCN5120 media module | Tapko Technologies | P.114.20.4611 | N/A | Only one media module required. Solution supports all |
| 15 | 1 | KNX PHY | N/A | Elmos E981.03 media module | Tapko Technologies | P.114.20.4011 | N/A | Only one media module required. Solution supports all |
| 16 | 1 | KNX PHY | N/A | Tapko KAIphys media module | Tapko Technologies | P.114.20.4511 | N/A | Only one media module required. Solution supports all |
| 17 | 1 | 430BOOST-SHARP96 | N/A | SHARP MEMORY LCD BOOSTERPACK | Texas Instruments | 430BOOST-SHARP96 | 296-38353-ND | |
| 18 | 1 | MSP-EXP430FR5969 | N/A | MSP430FR5969 LaunchPad Development Kit | Texas Instruments | MSP-EXP430FR5969 | N/A | |
| 19 | 1 | Y1 | N/A | Crystal 16.0000MHz 30ppm 18pF 40 Ohm | Abracom LLC | ABLS-16.000MHZ-B4-T | 535-10226-1-ND | Required in Launchpad for bit-based interface only |
| 20 | 2 | C3, C4 | 18pF | CAP CER 18PF 50V NP0 0402 | Kemet | CBR04C180F5GAC | 399-8828-1-ND | Required in Launchpad for bit-based interface only |

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